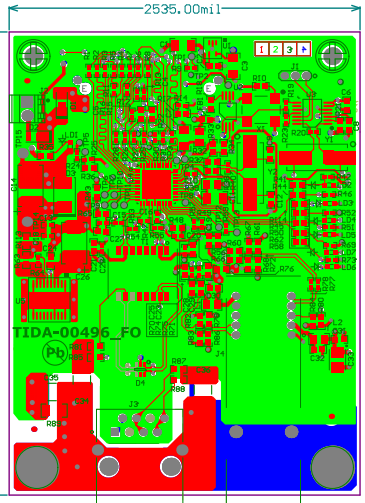
Layer Stack Up Detail for: TIDA-00496_FO.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	
L2_PI	(.G1)	1.4mil	FR-408
L3_P2	(.G2)	1.4mil	FR-408
Bottom Layer	(.GBL)	1.4mil	FR-408
Bottom Solder Mask	(.GBS)		Solder Resist

IMPEDANCE TABLE

LAYER	TRACE WIDTH	SPACING	IMPEDANCE	REFERENCE LAYER
TOP	7 MIL	16 MIL	100 OHM +/-10%	L2_P1
BOTTOM	7 MIL	16 MIL	100 OHM +/-10%	L3_P2



Symbol	Hit Count	Tool Size	Plated	Hole Type
B	107	12mil (0.305mm)	PTH	Round
A	96	16mil (0.406mm)	PTH	Round
C	49	20mil (0.508mm)	PTH	Round
H	10	31.89mil (0.81mm)	PTH	Round
G	9	32mil (0.813mm)	PTH	Round
D	2	33mil (0.838mm)	PTH	Round
F	8	35.039mil (0.89mm)	PTH	Round
I	2	40mil (1.016mm)	PTH	Round
M	2	44mil (1.118mm)	PTH	Round
K	2	55.118mil (1.4mm)	PTH	Round
E	2	57.087mil (1.45mm)	NPTH	Round
J	2	62.205mil (1.58mm)	PTH	Round
O	2	125.984mil (3.2mm)	PTH	Round
L	2	127.953mil (3.25mm)	NPTH	Round
N	2	128mil (3.251mm)	NPTH	Round
	291 Total			

Drill Table

DRILL TOLERANCES:

FOR PTH : +/-3MILS

FOR NPTH : +/-2MILS

FOR 12MIL DRILL VIA : +0/-12MILS

FOR 16MIL DRILL VIA : +0/-16MILS

1000 (mil)

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2535.00mil X 3346.46mil

Number of Layers : 4
MIN. TRACK WIDTH: 7 MIL
MIN. CLEARANCE: 7.8 MIL
MIN. VIA PAD SIZE: 26 MIL

MINIMUM ANNULAR RING 0.177mm (7MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
IT IS IMPENDANCE CONTROLLED BOARD

MATERIAL:
[X] FR-408 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES VIA TENTING: [ ] NONE [X] REQUIRED
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE:
IEEE1588 ethernet Brick_Fiber

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00496_FO.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00496_FO	REV: E1	SUN REV: Not In VersionControl	
LAYER NAME =				
PLOT NAME = Multilayer Composite Print	GENERATED : 9/23/2015 2:39:00 PM	TEXAS INSTRUMENTS		

ENGINEER:	LAYOUT BY:
Srinivas Kallikuppa	Avinash N
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.14.34663